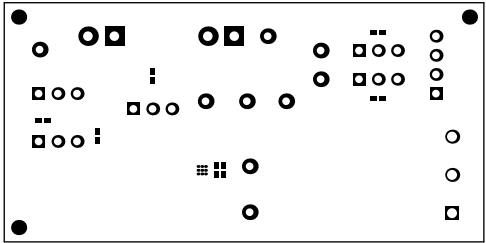
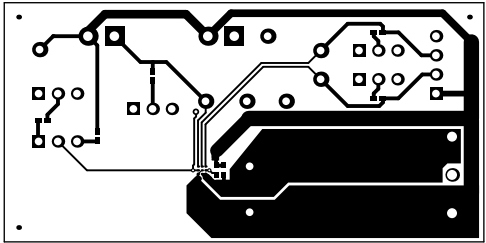


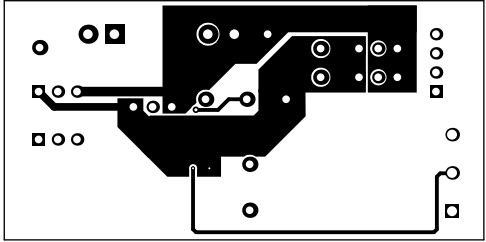
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR545	REV: C	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 2/20/2014 3:27:14 PM	TEXAS INSTRUMENTS	



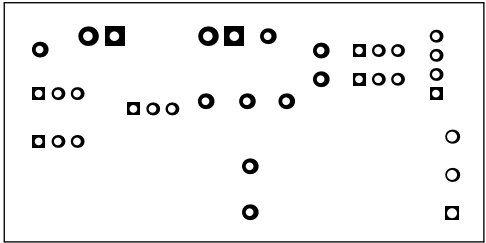
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR545	REV: C	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 2/20/2014 3:27:14 PM	TEXAS INSTRUMENTS	



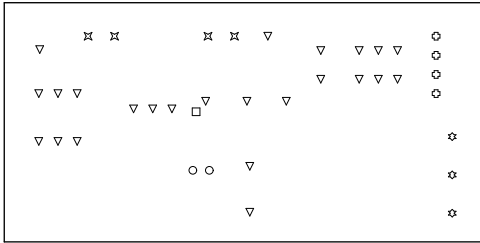
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR545	REV: C	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 2/20/2014 3:27:15 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR545	REV: C	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 2/20/2014 3:27:15 PM	TEXAS INSTRUMENTS	



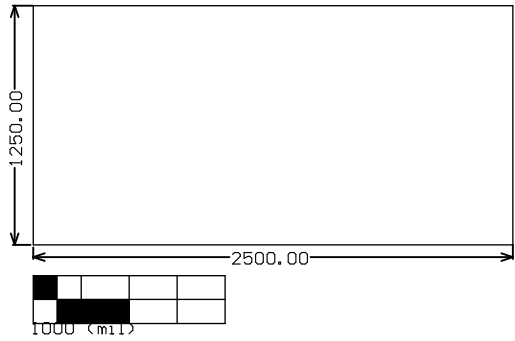
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR545	REV: C	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 2/20/2014 3:27:16 PM	TEXAS INSTRUMENTS	



Symbol	Hit Count	Tool Size	Plated	Hole Type
○	2	10mil (0.254mm)	PTH	Round
□	1	16mil (0.406mm)	PTH	Round
▽	24	40mil (1.016mm)	PTH	Round
⊗	4	40.157mil (1.02mm)	PTH	Round
⊗	4	50mil (1.27mm)	PTH	Round
☆	3	51.181mil (1.3mm)	PTH	Round
38 Total				

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR545	REV: C	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 2/20/2014 3:27:16 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PWR545	REV: C	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 2/20/2014 3:27:17 PM	TEXAS INSTRUMENTS	

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